FIG. 1 (Prior Art)

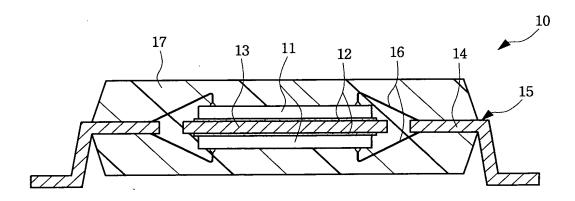
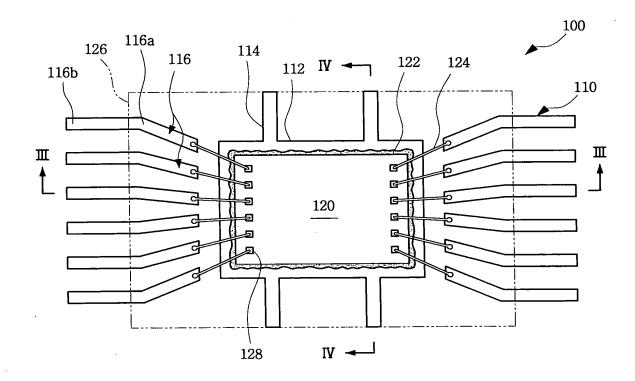


FIG. 2



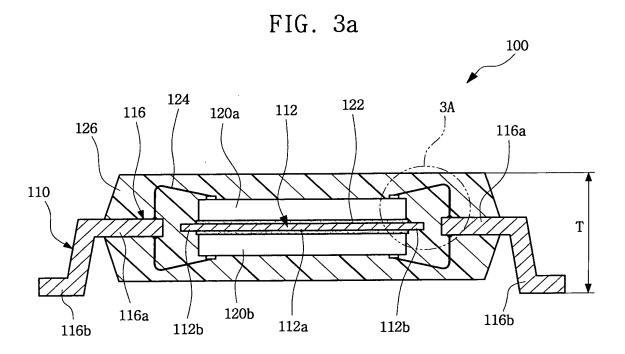


FIG. 3b

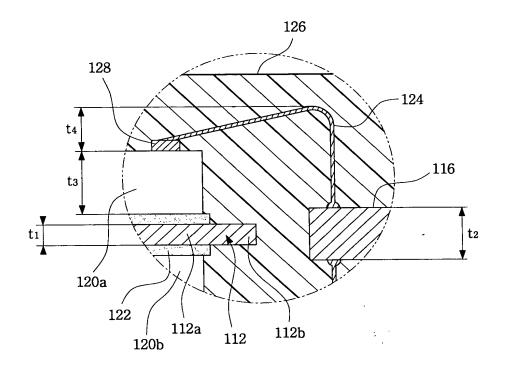


FIG. 4

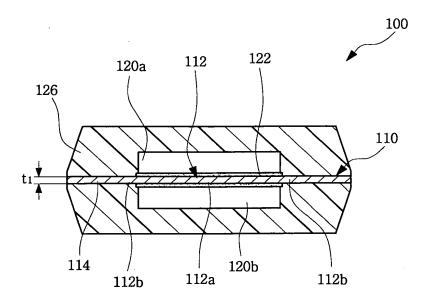
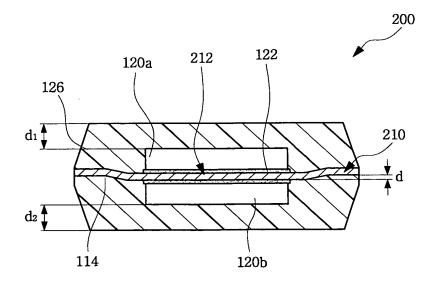


FIG. 5



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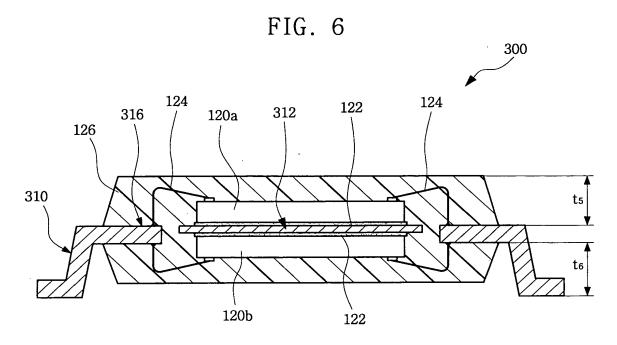


FIG. 7a

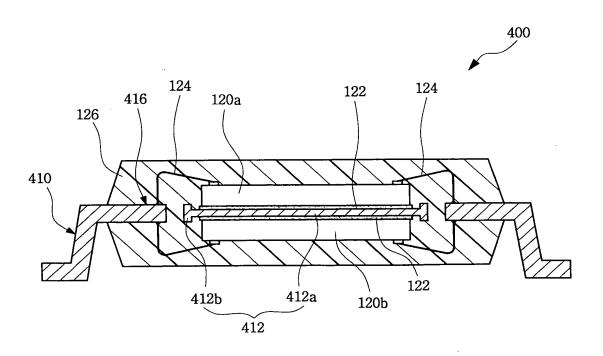
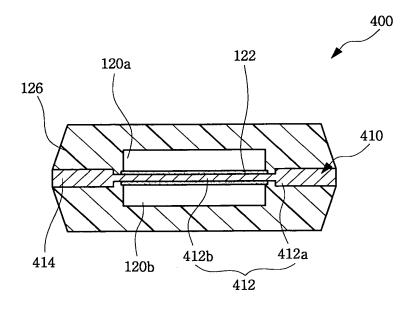


FIG. 7b



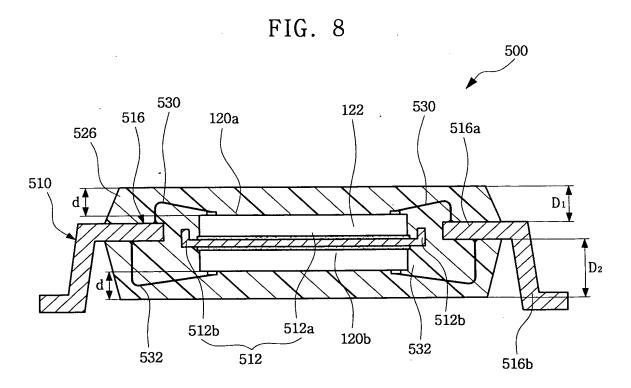
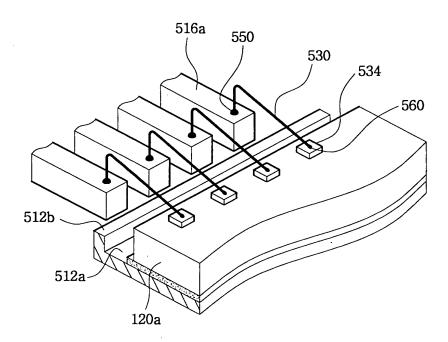
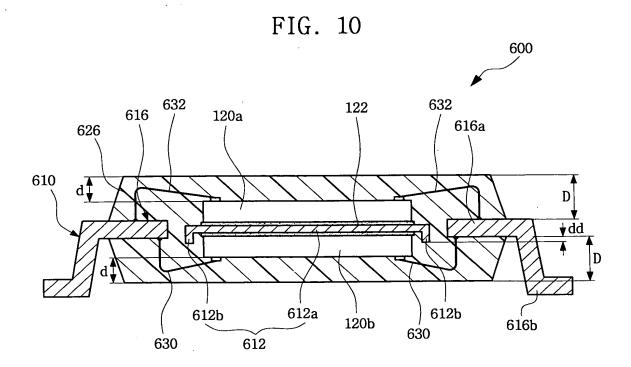


FIG. 9





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FIG. 11a

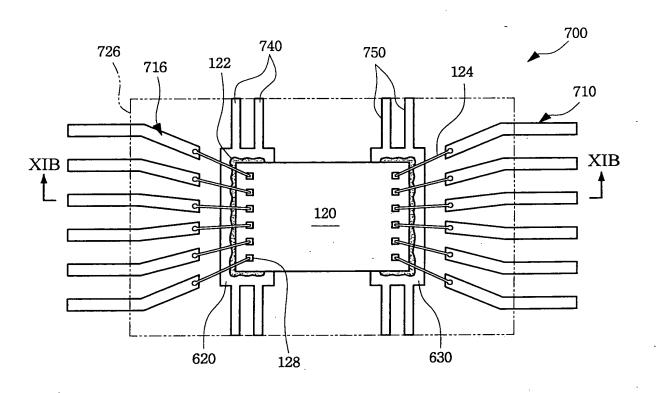
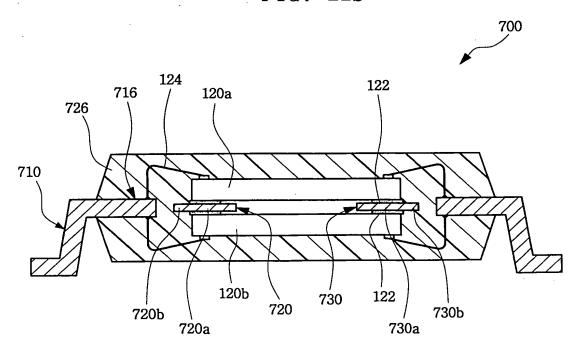
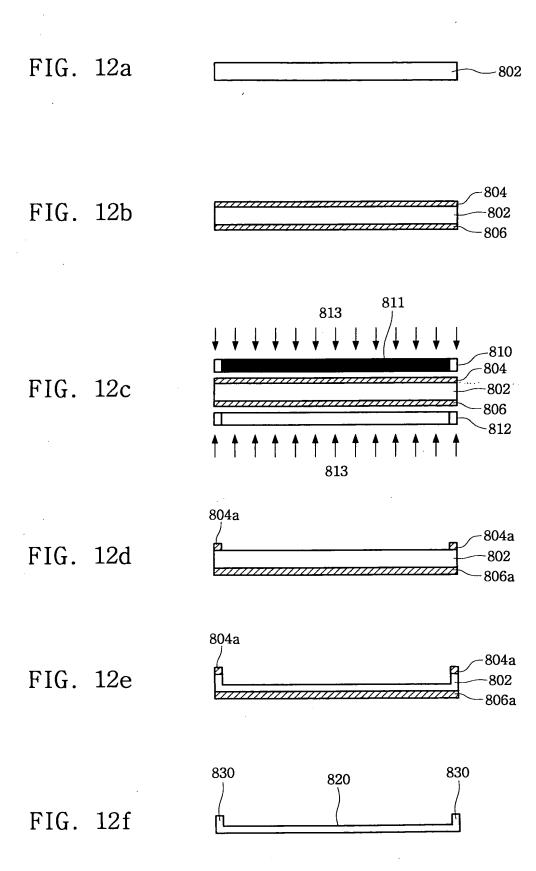


FIG. 11b





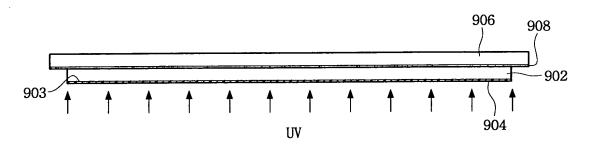


FIG. 13b

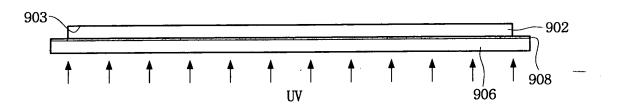


FIG. 13c

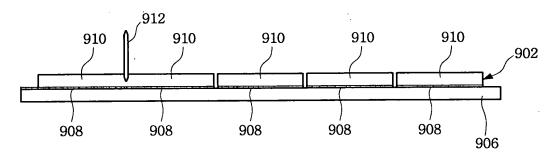


FIG. 13d

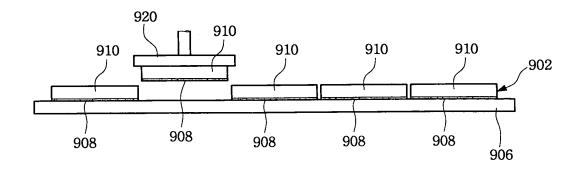


FIG. 13h

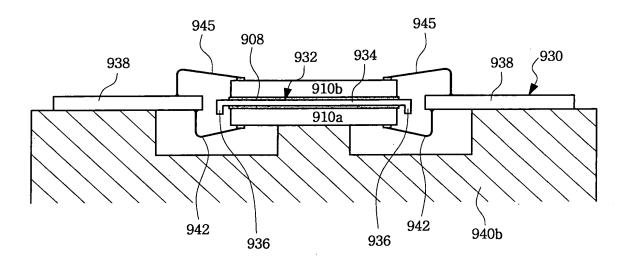


FIG. 13i

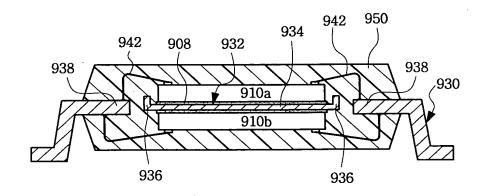


FIG. 13e

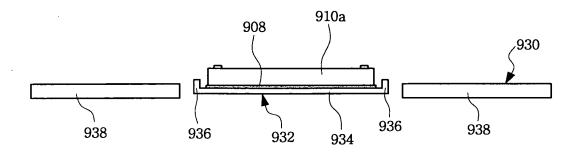


FIG. 13f

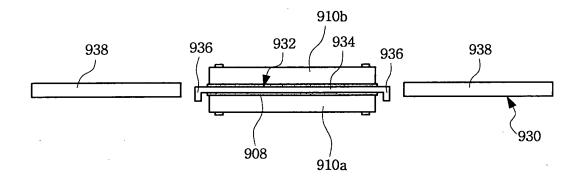
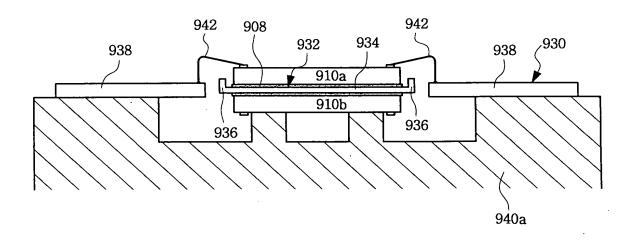


FIG. 13g



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FIG. 14a

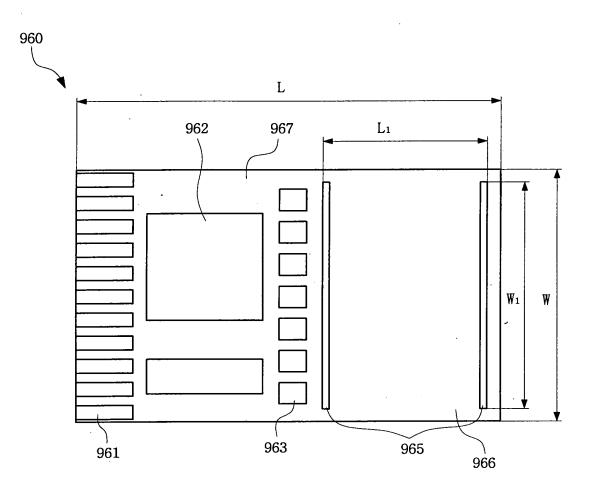
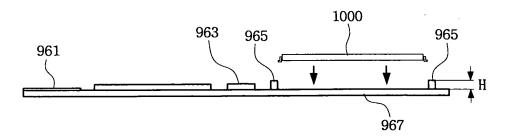


FIG. 14b



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FIG. 15

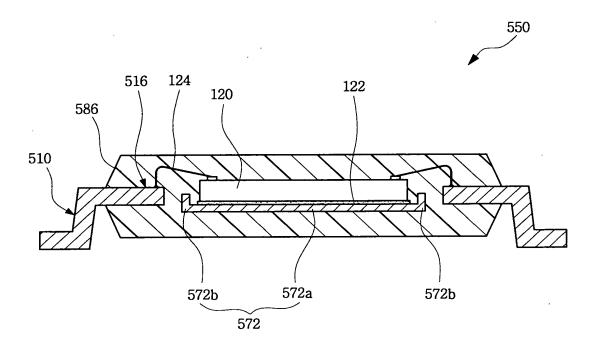


FIG. 16

